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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kling, et al.

Application No: 09/974,023

Filed: October 10, 2001

For: *Embedded Capacitor Multi-Chip  
Modules*

Conf. No.: 7890

Art Unit: 2814

Examiner: Hoai Pham

Atty. Docket: RAK-001.02

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I hereby certify that the foregoing documents are being deposited with the United States Postal Service as First Class Mail, postage prepaid, in an envelope addressed to Commissioner for Patents, Washington, D.C. 20231, on this 20<sup>th</sup> day of February, 2003.

  
Kerry Richard

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents  
Washington, DC 20231

**Attn: Official Draftsperson**

Sir:

Applicant hereby submits three (3) sheets of formal drawings containing Figs. 1-7 for the above-referenced application.

Should there be any questions after reviewing this paper, the Examiner is invited to contact the undersigned at 617-832-1175.

Respectfully Submitted,

Date: February 20, 2003

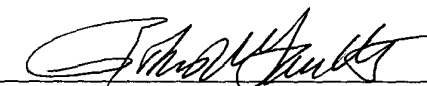
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